March 25th – 26th 2026
La Rochelle
France
Mercure Océanide
Vieux Port Sud
19th European Advanced Technology Workshop on Micropackaging and Thermal Management
Organized by IMAPS France - International Microelectronics Assembly and Packaging Society
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MAPS
More informations
www.france.imapseurope.org
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SERMA
MICROELECTRONICS
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12TH MICRO/NANO-ELECTRONICS PACKAGING AND ASSEMBLY, DESIGN AND MANUFACTURING FORUM
MiNaPAD
Forum
2026
June 3th – 4th
Minatec
Grenoble – France
▸ Exhibitions
▸ Conferences
TEC
iMAPS
Organized by IMAPS France – International Microelectronics Assembly and Packaging Society

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Welcome to THERMAL 2026

Dear conference Attendees, Speakers, Exhibitors and Visitors,

We are delighted to host this prominent European event focused on thermal management in microelectronics. The conference will take place on March 25th – 26th, 2026, at the MERCURE hotel in La Rochelle, France.

This international workshop provides a dynamic forum for both academic and industry leaders to exchange ideas, debate the state-of-the-art, and explore future trends in thermal management, from the package level to the system level.

The program is packed with content, including 1 invited keynote address from an academic leader, approximately 27 technical talks, and a technical exhibition featuring 19 exhibitors.

The enthusiasm from our industry partners has been exceptional, with the exhibition hall selling out nine months in advance. Attendees can look forward to enjoying French hospitality, including local cuisine and wines served throughout the exhibition space, fostering a warm and convivial setting for networking and collaboration.

While the industry may be reaching a point of financial maturity, technological innovation continues at a high pace, transforming electronic packaging, assembly, and system integration! We strongly encourage you to join us at THERMAL 2026 to learn about the latest global advancements and trends.

We look forward to seeing all of you in La Rochelle to exchange ideas and ensure this event remains the dynamic networking forum befitting the stature of our industry in Europe!

President of IMAPS France,

Alexandre VAL (VALEO)

General Chairmen:

Jean-Yves SOULIER (Safran Data Systems)

Jean-Pierre FRADIN (ICAM Toulouse)

Bruno LEVRIER (BL Expertises)

Steering Committee:

Sandrine LELONG-FENEYROU (Safran Data Systems)

Raphaël SOMMET (XLIM – Limoges University)

Vincent AYEL (PPRIME Institute, CNRS-ENSMA- Poitiers University)

Mohamad ABO RAS (NANOTEST)

REGISTRATION FORM ATW THERMAL MANAGEMENT

☛ **WORKSHOP FEES INCLUDE:**

2 days conference
2 nights Hotel (booked by IMAPS France)
Arrival on 24th March 2026, after 16h00
Departure on 26th March
All lunches and dinners from 24th March 8:00 pm (dinner) to 26th March 2026 4:00 pm

Registration to website: Imaps (https://event.imapsfrance.org)

- ☐ **IMAPS MEMBER** — **750 € VAT excluded**
- ☐ **IMAPS NON-MEMBER** — **850 € VAT excluded**
- ☐ **SPEAKER/CHAIR/TECHNICAL COMMITTEE** — **550 € VAT excluded**
- ☐ **STUDENT** — **550 € VAT excluded**
- ☐ **EXHIBITOR** — **580 € VAT excluded**
- ☐ **Additional night on 27th March** — **140 € VAT excluded**

HOW TO REACH DESTINATION OF CONFERENCE HOTEL

MERCURE VIEUX PORT

Quai Louis Prunier 17000 La Rochelle - France

Tel: 33 (0) 5 46 50 61 50

Email: H0569@accor.com.

Hotel reservations will be made by the organizing committee

Workshop arrival day:
Tuesday, 24th March 2026

sponsored by

Hotel Mercure Vieux Port

Quai Louis Prunier

17000 La Rochelle - France

46°09'13.7"N 1°08'58.2"W

By Car:

- From Paris: A10 Highway + N11 estimated duration 5h00
- From Bordeaux: A10 + A837 Highway; estimated duration 2h00

By Airplane:

- Airport Bordeaux - Mérignac (Arrivals and departures of the day | Bordeaux-Merignac Airport)
- Airport Rochefort : (La Rochelle - Ile de Ré airport: Flights, destinations & services)

By Train:

La Rochelle station : https://www.sncf-connect.com/en-en/

- 14 trains par day from Paris
  - **15h35 Paris-Montparnasse -18h13 La Rochelle** (suggestion)
  - 16h19 Paris Airport CDG2 TGV Roissy – 20h27 La Rochelle (suggestion)

  - **16h59 La Rochelle – 19h34 Paris – Montparnasse** (suggestion)
  -
- 10 Trains per day from Bordeaux
  - 16h52 Bordeaux – 19h28 La Rochelle (suggestion)

Other possibilities from Nantes, Tours,

5-6 minutes by walk to reach Train station from hotel

CONFERENCE SCHEDULE

DAY 1 - 25th March 2026 (Wednesday)

08:10 am

Opening address & table tops presentation

Jean-Yves Soulier, Conference chairman & IMAPS France Treasurer

08.15 am

KEYNOTE: Thermal management of wide-bandgap power semiconductor devices

C. Buttay

CNRS, INSA de Lyon, Université Claude Bernard Lyon 1 (France)

08:45 am – 09:40 am

SESSION 1: COOLING AT SYSTEM LEVEL

Chairs: B. Levrier, D. Saums

Introduction of liquid metal for highly dissipative processors for space applications

H. Garcia

Thales Alenia Space (France)

Thermal Characterization and Environmental Qualification of Oscillating Heat Pipes in VITA 48.2 Conduction Cooled Assemblies

C. Wilson

ThermAvant Technologies (USA)

09:40 am -10:10 am **Coffee Break / Table Top Exhibition**

10:10 am – 12:00 am

SESSION 2: MATERIALS

Chairs: A. Val, P. Couderc

New Sintering Materials: From Slit-Nozzle-Dispensing for Large Substrates down to Jet Dispensing for small Diodes

Dr. A. Stelzer, Dr. B. Rábay

Nano-Join (Germany)

Liquid metal TIMs for AI ASIC cooling

K. Vijay, M. Lazić
Indium (USA)

Aluminum–silicon alloys with tailored thermophysical properties for electronic´s cooling using silicon from photovoltaic waste

C. Vladu, E. Neubauer

RHP Technology (Austria)
Diamond potting

A. De Bibikoff, M. Tavares
Safran Data Systems (France)

12:00 am – 01:30 pm **Lunch**

01:40 pm – 03:00 pm **SESSION 3: MODELING & SIMULATIONS**

Chairs: JP. Fradin, JY. Soulier

Numerical study of PCM-copper foam composite for power electronics thermal management for different geometries and heat-flux density conditions

T. Lemonnier (1,2), H. Lescot (2), R. Rullière (1), C. Buttay (3)

(1) INSA Lyon, (2) Renault Group, (3) CNRS UMR5005

Optimization of Power module geometries for EV charging

J. Helie (1), Federico Ghioldi, Federico Piscaglia (2), Alexandre Marie, Jean-Pierre Fradin (3)

(1) Schaeffler (France), (2) Politecnico di Milano (Italy), (3) ICAM (France)

Transient Multiphysics Simulation of TVS Diodes

D. Frigerio (1), T. Bertoncelli, O. Ilina (2)

(1) Synopsys (Italy), (2) Synopsys (Germany)

03:05 pm – 04:30 pm **SESSION 4: 2-PHASE COOLING**

Chairs: V. Ayel, B. Levrier

Optimization of capillary mesh for thermal systems using additive manufacturing: exploration of design through different manufacturing strategies

D. Serret

TEMISTh (France)

03:30 pm – 04:00 pm **Coffee Break / Table Top Exhibition**

Overview for Electronics: Liquid Immersion and Pumped Two-Phase Dielectric Fluid Cooling

D. Saums

DS&A LLC (USA)

04:30 pm – 05:55 pm **SESSION 5: CHARACTERIZATION & TESTS**

Chairs: JP. Fradin, M. Sabah

Effect of Surface Roughness on the Thermal and Reliability Performance of Thermal Interface Materials

A. Reinke, A. Harder, S. Campos-Böttges, P. Zimon, T. Bräuer, M. Abo Ras

Berliner Nanotest und Design GmbH (Germany)

Understanding the measurement of the temperature in GaN HEMTs : Overview of measurement techniques and results

M. Boussekri, J-C. Nallatamby, R. Sommet (1), K. Karrame (2), C. Chang (3)

(1) XLIM, (2) ICAM (3) UMS (France)

Thermal Investigations of GaN layers on foreign substrates for vertical power devices

L. Mitterhuber, V. Leitgeb, B. Kosednar-Legenstein, E. Kraker (1), F. Brunner, E. Bahat-

Treidel (2)

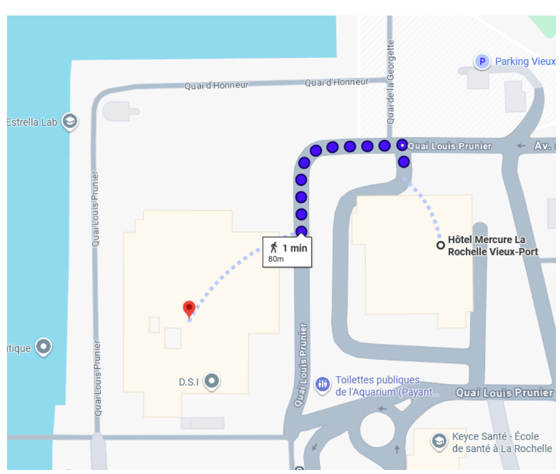
(1) Materials for Microelectronics, Materials Center Leoben Forschung GmbH, Leoben, (Austria),

(2) Ferdinand-Braun-Institute Berlin (Germany)

05:55 pm **End of 1st day Sessions / Tabletop Exhibition**

06:30 pm – 10:00 pm **Social Event: Aquarium & Dinner**

Visits will start at 6:30pm : 1 minute by walk from Mercure Hotel



DAY 2 - 26th March 2026 (Thursday)

08:10 am – 10:00 am

SESSION 2bis: MATERIALS

Chairs: A. Val, P. Couderc

Performance and reliability of aluminium cold plates: A comparison between FSW and Brazing

L. Dubourg, K. Aznar, V. Pecqueur

Stirweld (France)

Review of strategies to achieve high thermal conductivity encapsulating materials for electronic devices

R. Khazaka, S. Azzopardi

Safran (France)

Thermal dissipation solution for GaN applications: BIONIC project

E. Barbier, E. Elrifai, S. Mathieu, M. Coulon

Egide (France)

Advanced Phase Change Thermal Interface Material with Reduced Pump-Out Risk for high reliability thermal management applications

D. Pudolin

Krayden Europe (Netherlands)

10:00 am – 10:30 am **Coffee Break/ Table top Exhibition**

10:30 am – 12:15 pm

SESSION 4bis: 2-PHASE COOLING

Chairs: B. Levrier, D. Saums

Direct two-phase cooling of semiconductors: influence of flow regime and mass flow on local heat transfer coefficient

A. Loehrmann, O. Crepel (1), E. Videcoq, V. Ayel (2), S. Dutour (3)

(1) Airbus SAS, (2) PPrime Institute, CNRS-ENSMA Poitiers (3) LAPLACE, UPS, INPT, CNRS, Université de Toulouse (France)

Pulsating heat pipes for equipment thermal management

F. Kilinc, M. Sabah (1), V. Ayel, N. Riaud (2)

(1) Safran Electronics and Defense, (2) PPRIME INSTITUTE, CNRS – ENSMA – UNIVERSITÉ DE POITIERS (France)

A new regime of stable two-phase heat transport without oscillation in meander shaped low-fill heat pipes

K. Fumoto, A.Hatamoto

Aoyama Gakuin University (Japan)

Vibration effects on the performance of the heat pipe for aeronautical electronics packaging equipment

M. Sabah

Safran Electronics and Defense (France)

12:15 pm – 01:40 pm **Lunch**

01:50 pm – 02:45 pm **SESSION 5bis: CHARACTERIZATION & TESTS**

Chairs: JP. Fradin, A. Reinke

Power-Cycling Test Methodology to Investigate TIM Degradation Under Varying Interface Configurations for High-Performance Computing Using Thermal Test Vehicles

J. Haseloff, M. Sternberg, D. Wargulski, M. Abo Ras

Berliner Nanotest und Design GmbH

Critical Improvements in Thermal Materials and Characterization Tools

D. Saums

DS&A LLC (USA)

02:45 pm – 03:40 pm **SESSION 3bis: MODELING & SIMULATIONS**

Chairs: JP. Fradin, JY. Soulier

Development of reduced order models (ROM) based on thermal simulations for thermal design of LED products on FR4 boards

A. Andres (1), V. Shanbhog (2), J. Jiajin Wu (3)

(1) Valeo (Spain), (2) Valeo (India), (3) Valeo (China)

Automated toolbox for thermal modelling of printed wiring assemblies

M. Ali, S. Salvadori (1), V. Singh, A. Battentier (2)

(1) SLB (France), (2) SLB (USA)

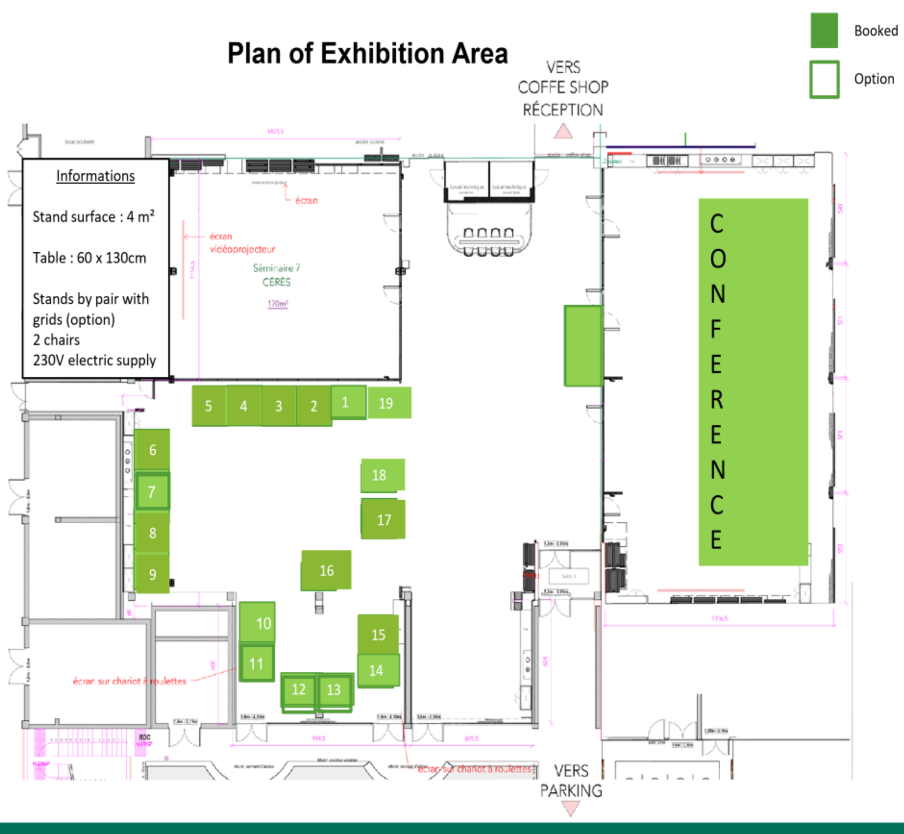
03:45 pm – 03:50 pm **Closure**

Final coffee break and farewell

EXHIBITORS

Exhibitor Name	Logo	BOOTH
ACCELONIX		2
APR Technologies		19
ATHERM		6
BOYDCORP		1
CCI EUROLAM		7
dB&DEGREES		18
HENKEL		9
INVENTEC		14
KYOCERA		10
METRONELEC		3
MICRONOR		4
NANOTEST		12
RHP		13
SERMA Microelectronics		16
SIEMENS		11
STELIAU		8
TEMISTH		15
THERMAVANT		5
WATTDESIGN		17

PLAN OF EXHIBITION AERA



ACCELONIX

BOOTH 2

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www.accelonix.fr_

Activities

Accelonix is a solutions provider of equipment, materials and software for electronic & micro-electronics assembly.
Accelonix group focus is western Europe, for industrial and research institutions, working in all sectors of the electronics industry.
Our service is based on close partnership with all Accelonix suppliers, through exclusive agreements in combination with in-house technical team, permuting rapid and efficient customer services and technical support.
Our success is built on an attitude for « innovation & opportunity » in synergy with a mix of complementary products and technologies. It is our intention that our customers benefit directly from this synergy, in addition to our contact and experience base, built up from over 25 years existence of Accelonix, and many decades of industrial experience for those in the company.
In addition to activities in Micro-assembly, Accelonix France is also active in the domains SMD pcb assembly and test, and Hi-rel component supply.

Product

- dicing – wafer, glass, ceramic, composite
- dispensing & jetting – pumps and machine for glue, solder, glob top, underfill,
- die attach and die sorting: MCM, Hybrid, silver glass, flip chip, eutectic
- wire bonders: manual & Automatic; fine & heavy; wedge & ball
- Battery bonding (Wirebonding, Smartwelding, Laserwelding)
- back-end plasma process – batch, on-line for wirebond and surface treatment
- vacuum pressure furnace – low void, flux free solder & brazing & wafer bonding
- hermetic sealing – seam sealing
- clean room & dry cabinets – modular and integrated solutions
- modular bond test – pull, shear, flex, stud pull
- screen printing – for ceramic substrates

Equipment for Metrology

- Non-surface contact profilometry
- Thémal warpage metrology

APR Technologies

BOOTH 19

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Activities

APR Technologies develops advanced liquid cooling solutions for high-performance semiconductor devices and heterogeneous integrated systems. The company specializes in dielectric near-chip cooling technologies, including direct-to-chip cooling, integrated micro-cooling with embedded micropumps, and advanced immersion cooling, designed for close thermal coupling with advanced semiconductor packaging such as chiplet-based architectures, interposers and 2.5D/3D integrated packages.

By bringing liquid cooling directly to the component and chip level, APR enables efficient removal of very high heat fluxes, supporting increased power density, improved energy efficiency and stable long-term operation compared to conventional air- and water-cooled approaches. The solutions address key thermal challenges in advanced packaging for AI accelerators, high-performance computing and telecom systems, where thermal management increasingly limits performance, reliability and scalable deployment.

Headquartered in Enköping, Sweden, APR Technologies is in a scale-up phase, expanding its technology platforms into new markets while supporting the growing demand for scalable and sustainable thermal solutions for next-generation semiconductor packaging and data center architectures.

Products

APR Technologies offers a portfolio of deployable liquid cooling products translating chip-near thermal architectures into system-lvel solutions for next-generation electronics and data center infrastructure:

• Dielectric single- and two-phase immersion cooling systems for high-density servers and high-power electronics, engineered for improved local heat removal without aggressive bulk over-cooling

• Integrated near-chip cooling modules and component-level solutions, delivered as **hardware-to-integrate**, enabling improved thermal contact and reduced junction-to-coolant ΔT

• Dielectric fluid-based cooling solutions supporting **safe direct-contact interfaces at package and component level**, compatible with advanced semiconductor packaging and heterogeneous integration

• Scalable and modular cooling platforms designed for AI accelerators, HPC, telecom and edge deployments, supporting high heat-flux operation and stable long-term performance

• Solutions optimized for **low pumping power, high energy efficiency, simplified system integration and extended system lifetime**

APR’s products enable higher operating temperatures and reduced system-level cooling overhead, supporting scalable deployment of high-density semiconductor systems with lower total energy consumption and environmental impact.

ATHERM

BOOTH 6

Activities

Atherm was founded in 1988 by experts in thermal design. Today, as a worldwide leader, we are fully committed to developing innovative thermal solutions for the industry. Our R&D team and ISO9001 industrial manufacturing plant are located in Grenoble, France.

Atherm manufactures Liquid Cold Plates**,** Heatpipe systems, Heatsinks with heatpipes according customers specifications. Our expertise involves the development, design and calculation and the prototyping and serial manufacturing.

Our applications are dedicated to power electronics, embedded electronics, aeronautics, batteries, energy efficiency and all other devices, installations & markets impacted by thermal management.

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Boyd Technologies Ashington UK Ltd

BOOTH 1

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www.boydcorp.com/
www.boydcorp.com/about-boyd/locations/boyd-europe-locations.html

boydcorporation/

company/boyd/

Activities

Boyd Technologies (Ashington) UK Ltd designs and manufactures advanced thermal management solutions for demanding applications.
We support electronics cooling from concept and simulation through prototype and full-scale production.
Our portfolio includes liquid cold plates, Heatpipe, direct-to-chip solutions, and high-performance heat exchangers.
We develop and build heat pipes, vapor chambers, and other two-phase heat transfer devices.
Our solutions target power electronics, inverters, traction, and energy storage systems.
We support aerospace and defence programs with robust, qualification-ready hardware.
Manufacturing is done all in-house in the UK, with qualified plant space for space and aerospace programs.
The site operates under ISO 9001 and AS9100 quality management systems.
We deliver custom engineering to meet size, weight, reliability, and acoustic constraints.
We help customers optimize performance with test, characterization, and iterative design.
We can integrate cooling hardware into complete modules and sub-systems.
Our goal is to enable higher power density, better reliability, and lower total system cost.

Products

Thermal, fluid, materials, and structural analysis to optimize performance and reliability.
Design support from early concept through detailed engineering and industrialization.
Prototype fabrication with fast iteration to validate form, fit, and function.
Testing, qualification, and production testing delivered with defined ITP (Inspection and Test Plans).
Two-phase cooling and phase-change thermal control for high heat-flux applications.
Heat pipes for efficient, passive heat transport over distance.
Vapour chambers for heat spreading under compact footprints.
Special high-performance heat sinks for extreme power density and constrained airflow.
Loop heat pipes and loop thermosyphons for robust, low-power thermal management.
AGHP, CCHP, and ammonia heat pipes for demanding space environments.
Liquid cooling solutions engineered for power electronics and high-reliability systems.
Vacuum-brazed cold plates for high thermal performance and leak-tight assemblies.
Friction Stir Welding (FSW) cold plates for robust, high-strength liquid circuits.
Tube-in-plate (serpentine) cold plates and complete liquid chassis for aerospace integration.
Advanced conduction and graphite technologies, including k-Core® APG and flexible straps, plus Solimide polyimide foam for lightweight aerospace and naval insulation.

CCI EUROLAM

BOOTH 7

Activities

CCI Eurolam is your EMEA partner for the supply of special materials and chemicals for the electronic industry. We are waiting for your visit on our booth to present our suppliers latest innovations for electronic design and manufacturring including :

Latest generation of Indium Corporation materials for soldering, fluxing, sintering and thermal dissipation from semi-conductor level to Pcba assembly.

Products

Microelectronics and semiconductor packaging :

- Qunity metallization for UBM, RDL, Cu pillars as well as polymers and dielectrics for RDL.
- Photolithography resins and solutions for developing, cleaning and eteching.
- Tatsuta bonding wires.

Pcb materials & chemicals :

- Emc latest generation of Pcb substrate to meet microwave, low loss requirements as well as high performances, high Tg and IC substrate.
- Qunity plating, developing, striping,
- Dry film,
- Process equipment.

Electronic inks :

- Micromax functional inks and substrate for printed electronics (heating, stretchable, thermoforming, PI resistive,…). "Grenne Tape" LTCC and high temperature "thick film inks" inks.
- Piezotech inks.
- Agfa Pedot PSS based materials.

Adhesive :

- Bostik adhesive solutions for the electronics.

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dB & DEGREES

BOOTH 18

Activities

We support our customers **from the definition of a technical challenge to the delivery of a fully functional part or assembly in France or abroad**.
Our approach covers the entire project life cycle, from design to industrialization, integrating thermal management and electromagnetic compatibility (EMC) solutions.
We work on projects with high technical constraints in the **aerospace, defense, marine, space, land, automotive, and telecommunications fields.**
These environments require high levels of performance, reliability, and compliance with applicable standards.
The design choices for specific parts are supported by multiphysical simulations that we carry out in-house using technologies we have mastered, enabling us to model a complete industrial solution that can then be manufactured by us. When certain special processes require it, such as painting or surface treatments, we work in partnership with local partners.
Particular attention is paid to quality, within the framework of an ISO 9001 and ISO 14001 certified management system.

Products

1. **Mechanical parts (general):**
   - Precision machined parts on which we will place EMC seals, thermal interfaces, or both.
2. **Mechanical parts for thermal dissipation:**
   - Heatsinks and heat spreaders, Machined cold plates up to 2 m. Heat Pipes, Vapor Chambers
3. **Mechanical parts for EMC:**
   - Metal gasket (Photo-etching)
   - Shielding covers and frames, vent panels, Shielding windows
4. **Thermal interfaces:**
   - Form-In-Place (FIP), thermal conductive materials (Dispensing by robots)
   - PCM, graphite pads, ultra-soft or high-conductivity material
   - Oriented carbon nanotube pads
5. **EMC Gaskets:**
   - Co-extruded gaskets and Oriented wire gaskets
   - FIP Gasket (Dispensing by our robots)

All these products can be modified, customized, and sometimes even combined to meet your specifications.

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HENKEL ADHESIVE TECHNOLOGIES

BOOTH 9

Activities

Henkel is a global company with a long history of innovation, operating across both industrial and consumer markets with a strong focus on sustainability and worldwide brand leadership. Its largest division, Adhesive Technologies, is recognized as the world's leading provider of adhesives, sealants and functional coatings, serving hundreds of industries and driving forward digitalization and sustainability initiatives such as advanced environmental assessment tools and end-to-end transparency. The Adhesives Technologies business unit has built a reputation for transformative solutions across automotive, electronics, manufacturing and many other sectors, reflecting Henkel's broader commitment to innovation and responsible growth.

Products

From structural adhesives to surface preparation and new lightweight materials, Henkel supports manufacturers in redefining air travel with the LOCTITE® and BONDERITE® brands. Unlock peak performance for your electronic devices and applications with LOCTITE® Bergquist® thermal management materials. Our advanced solutions optimize functionality and enhance reliability, ensuring superior performance. Henkel's LOCTITE® Bergquist® thermal management materials, including GAP PAD® materials, SIL PAD® materials, phase change materials, microTIMs, LIQUI-FORM® products, and thermal adhesives, tackle today's toughest thermal management challenges. Manage heat more effectively every step of the way with a thermal management material suitable for any and every application.

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(23) Henkel Adhesive Technologies : Présentation | LinkedIn

INVENTEC PERFORMANCE CHEMICALS

BOOTH 14

Activities

Inventec Performance Chemicals, with headquarter in France (Paris), is a global B2B provider of Electronic Assembly Materials, Precision Cleaning Fluids, Protective Coatings and Thermal Management Fluids.

For over 60 years we have shown leadership in innovation by putting HEALTH IMPACT, SUSTAINABILITY and RELIABILITY at the core of our product development. With more than 300 products in our portfolio, we serve over 1800 customers.

With 16 subsidiaries and ISO 9001 & 14001 production sites in France, Switzerland, USA, Mexico, Malaysia and China we can guarantee a smooth and cost-effective supply chain across the globe. Trusted across many industries, our solutions excel in automotive, aerospace, semiconductor, energy, and medical applications where reliability matters most.

Products

PRODUCT RANGES:

- **Electronic Assembly:** solder paste, sinter paste, fluxes, powders,
- **Precision cleaning**: solvent & aqueous based cleaning fluids for electronic and mechanical applications
- **Protective coatings:** ultra-thin (nano coatings), conformal and epilame coatings
- **Thermal Management:** Cooling fluids for immersion, direct & direct-to-chip and manufacturing processes.

HIGHLIGHTED PRODUCTS & SERVICES

- **ECOREL™ SINTEC:** sinter paste based on Nano-Join technology
- **PROMOSOLV™ NEO**: PFAS FREE, Zero GWP & non-flammable cleaning solvents
- **ECOREL™ 305-F1:** solder paste dedicated for formic acid reflow (other alloys available)
- **ECOREL™ JP32:** solder paste dedicated for Jet Printing process
- **THERMASOLV™ IM2:** dielectric fluid dedicated for datacenter immersion cooling
- **ECOPROGRAM™:** recycling service for end-life cleaning and cooling solvent-based fluids

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KYCERA

BOOTH 10

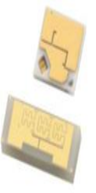
Activities

High-reliability ceramic packages and substrates help to miniaturize components used in smartphones, fiber optics, automotive electronics (such as headlight LEDs), and a wide range of other applications. Materials, processing, and design technologies to ensure unparalleled substrate and package performance.

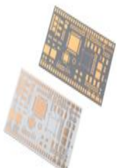
Ceramic Surface-Mount Packages for Electronic Devices

Ceramic Packages for Image Sensors

Optical Components



Ceramic Packages for LEDs



Multilayer Ceramic Substrates for Automotive ECUs

The rapid advancement of information and communications technologies (ICT) and the internet have fueled an extraordinary increase in the functionality and performance of electronic devices. Our organic packages help to support these developments.

Flip-Chip Packages

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METRONELEC

BOOTH 3

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METRONELEC | LinkedIn Building
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Activities

METRONELEC is a longstanding French player in the electronics and microelectronics sectors, founded in 1975. The company designs, manufactures, and distributes high-performance equipment dedicated to the production of electronic boards, advanced micro-assembly processes, and the quality control of sensitive components.
Thanks to its recognized expertise in inspection, soldering, characterization, and metrology control solutions, METRONELEC supports industrial players across a wide range of fields such as microelectronics and semiconductors. The company supplies high-precision bond testers, quality control equipment, as well as optical and X-ray inspection systems. METRONELEC is also active in electronic PCB assembly, offering high-precision screen printing equipment, pick-and-place machines, reflow ovens, and 3D AOI inspection systems. In addition, the company helps strengthen process control and reliability through dedicated solutions including solderability testers, ionic contamination analyzers, and coating thickness inspection systems. Finally, METRONELEC develops advanced integration solutions designed for the most demanding electronic production lines, incorporating robotics, autonomous transport systems (AGV/AMR), and inline inspection. With nearly 50 years of experience, an international presence (France, China, Tunisia, Morocco), and a global network of specialized distributors, METRONELEC provides comprehensive technical support including installation, commissioning, training, and maintenance.

Products

METRONELEC offers a comprehensive portfolio of equipment covering the entire electronic and microelectronic manufacturing cycle:

- High-precision bond testers for the mechanical characterization of critical microelectronic interconnections.
- 3D AOI inspection systems and X-ray equipment for fine defect detection in production.
- High-precision screen-printing machines ensuring reliable and reproducible paste deposition.
- High-speed component placement systems for complex electronic assemblies.
- Ionic contamination testers and solder quality control equipment.
- Laser marking solutions and soldering equipment for demanding applications.

These technologies directly address the needs of the following sectors:
microelectronics, advanced circuit assembly, semiconductors, industrial equipment manufacturers, defense, telecommunications, and other critical applications.

MICRONOR

BOOTH 4

Activities

More than 50 years as **subcontractor expert in custom hermetic sealing & hermetic interconnections** for harsh environment (pressure, intensity, tension, temperature, etc…)

Design and production of prototypes, small and medium series, **based on customer technical specifications**.

Small size of pieces (Ø 0,2 mm up to 150 mm)

- **Glass to Metal seal** (including dilver P1 (kovar) and titanium) and **high and low temperature brazing** (ceramic, sapphire, etc…)
- Base and **precious metals electroplating (specific 99,99% pure gold for space applications)**
- Hermeticity : **Leak rate less than 10^{-8} mbar.l/s**
- Electric isolation : Isolation resistance over 10 GΩ
- Breakdown voltage : from 500 to 3000 V
- Pressure : up to **3000 bars**
- Operating temperature : **from -180°C to +300°C** (according to coating)

Precious metal electroplating processes (gold, silver) and common metal (tin, copper) for industrial applications (space, defense, etc…) – specific **99.99% pure gold electroplating** process for space application.

Products

Non exhaustive products list (based on customer's technical specifications) : feedthroughs, electronic packages, sensors, relay bases, connectors, isolators, igniters bases, medical implants etc…

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NANOTEST | Berliner Nanotest und Design GmbH

BOOTH 12

Activities

NANOTEST | Berliner Nanotest und Design GmbH is a German engineering company with an in-house scientific laboratory providing services and products for thermal characterization as well as for measuring, improving, and maintaining reliability. Serving all areas of the electronics industry from RF to high-power devices, and from automotive to aerospace and space applications. Nanotest delivers solutions that enable material and system manufacturers to enhance product quality, performance, and reliability.

Products

NANOTEST products combine scientific depth with practical usability, ranging from simple single measurements to partially automated series testing, aging studies, and failure analysis. Nanotest offers customized Thermal Test Vehicle (TTV) development services tailored to specific customer requirements, as well as off-the-shelf TTV solutions, including dedicated measurement hardware and software. Through active research and close collaboration with institutes and universities, Nanotest solutions remain aligned with the latest scientific and methodological advances.

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RHP-Technology GbmH

BOOTH 13

Activities

RHP-Technology GmbH is an Austrian innovator in advanced materials and powder-based processing, headquartered in Seibersdorf. Founded as a spin off from the Austrian Institute of Technology, RHP delivers rapid development, prototyping, and small series production as well of production of customized products made from metals, ceramics or their composites as well as nanostructured materials. Core technologies include spark plasma sintering (SPS), hot pressing, additive manufacturing (inclusive plasma metal deposition) and powder injection molding. The product portfolio includes customized sputtering targets for thin film deposition as well as products for high tech sectors such as heat sink materials for electronics, ceramics used in semiconductor industry.

Products

Heat sink materials based on metal-diamond composites as well as fiber reinforced metals

Sputtering targets: standard and customized compositions with backing and assembly

Product development for advanced ceramics

Advanced manufacturing services: SPS, hot pressing, plasma metal deposition, AM for complex, multi material, and graded structures, injection moulding to serve the development of new products

Customized materials: high entropy alloys, MAX phase materials, ceramic metal composites, radiation resistant and functional advanced materials

Fast track material and process development, prototyping, and pilot production with transfer to full size production.

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RHP-Technology GmbH | RHP

SERMA Microelectronics

BOOTH 16

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company/serma-microelectronics/

Activities

SERMA Microelectronics develops and provides special processes to manufacture ceramics substrates and integrate semiconductors.

Taking advantage of its strong knowledge and skills in components assembly, in ceramics, metal, and now organic material, SERMA Microelectronics helps its customers and partners in the tuning of integration processes, allowing the use of a technology on a specific mission profile.

With more than 90 employees gathered on 2 productions site in Périgny (la Rochelle) and Pinsaguel (Toulouse) counting 1000 sqm clean room, SERMA Microelectronics offers 5 main activities:

Engineering, that defines the right microelectronics integration processes in order to industrialize products for customers.

Die Management, managing the dice flows (supply, storage, wafer sawing, dies visual inspection)

Microelectronics production, implementing the manufacturing & test processes to produce customers goods.

Thick film production, defining and implementing screen-printing techniques to produce thick film substrates with high temperature resistance and service life.

Thin film production, using sputtering techniques at the edge of front-end technology, to implement metallic deposition of high precision (nanometric scale).

The variety of processes available within SERMA Microelectronics allows addressing various markets and technologies. SERMA Microelectronics works on maintainability issues by maintaining robust process and securing their availability through time, and focus its R&D efforts on the development and deployment of technological bricks to integrate up-to-date technology (MEMS, High pin count devices, BGA, UBM, RDL) and mix its microelectronics means and SMT capabilities to integrate SiP (System in Package)

Siemens Digital Industries Software

BOOTH 11

SIEMENS

Activities

Transform engineering with Simcenter and Altair
Leverage the most comprehensive, intelligent and integrated simulation and test portfolio to tackle your engineering challenges. Accelerate innovation by combining simulation, engineering data science and AI. Drive faster, smarter decisions with integrated solutions for enterprise collaboration.

Products

- **Simcenter Micred hardware:** Enhance semiconductor package thermal quality with a test solution combining precise thermal characterization with high throughput automatic evaluation and binning.

- **Simcenter Flotherm software :** Improve electronics thermal management for reliability with fast, accurate electronics cooling CFD simulation from initial pre-CAD exploration to final verification.

- **Simcenter FLOEFD software :** Leverage fully CAD-embedded CFD software for designers to shorten development by evaluating fluid flow and heat transfer earlier in NX, Solid Edge, CATIA and Creo.

- **Power Electronics and Motor Drive Software | Altair® PSIM™ :** Complete solution for designing and validating power-conversion systems, from concept to hardware implementation.

- **Altair® PollEx™ for ECAD**: Free PCB verification tools to improve design quality through early analysis and manufacturability checks

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(7) Simcenter : Présentation | LinkedIn

STELIAU TECHNOLOGY

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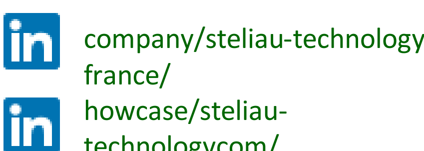
company/steliau-technology-france/
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Activities

Founded in the 1990s, Steliau Technology started as a value-added distributor and supplier of electronic solutions in the European electronics market, specializing in key areas such as Human-Machine Interfaces, Display, Connectivity (IoT, M2M, Positioning), Mechatronics, Embedded Systems, OEM/ODM, Heat dissipation solutions, Energy conversion, and Electronic components solutions (Semi, Passives & Electromechanical).

Steliau Technology has built a strong reputation in its market, maintaining long-standing relationships with its customers. Partnering with global suppliers—often leaders in their respective market segments—Steliau Technology offers top-quality products known for their durability and performance. Its experienced sales teams seamlessly integrate into the sales force of the manufacturers it represents across Europe.

By combining its European territorial expansion with a commitment to local service, personalized support, and regional integration sites, Steliau Technology ensures customer-centric operations. With over 350 suppliers represented, Steliau Technology provides a comprehensive range of products and tailored solutions to more than 2,000 customers in diverse industries, including Industry 4.0, Internet of Things, AI, Consumer & Home Appliances, e-Mobility & Green Energy, Automotive, Space/Aero, Medical, and Public Transportation.

Since 2016, Steliau Technology has pursued an ambitious external growth strategy, acquiring several significant European companies and establishing itself as a leader in integrated electronic solutions.

Products

Steliau Technology is able to provide complete thermal management solutions, including thermal pads, heat sinks, cooling modules, gaskets, and fastening systems.

With a wide range of thermal interface materials (insulation films, gap pads, thermal adhesives, phase-change materials, etc.) and an in-house cutting room located at its Rungis facilities, Steliau Technology offers several services: thermal studies and simulations, custom cutting, kit assembly, CAD design, and rapid prototyping (48-hour turnaround). The assembly of thermal pads and heat sinks can also be handled by our teams. Altogether, this approach delivers a comprehensive solution, from design through to final integration.

TEMISTH

BOOTH 15

Activities

Situés dans le sud de la France, nous sommes spécialisés dans l'ingénierie et la fabrication d'échangeurs et dissipateurs thermiques innovants. Depuis 2012, nous proposons des solutions adaptées grâce à des procédés de production de pointe tels que la fabrication additive métallique, le soudage par friction et une offre de conception sur mesure.

Products

Nos technologies permettent de concevoir des solutions plus légères et intégrées, répondant à des applications variées : plaques froides, chambres à vapeur, stockeur PCM, échangeurs cryogéniques ou pour hautes températures.
Notre équipe pluridisciplinaire regroupe l'ensemble des savoir-faire indispensables à la conception de systèmes thermiques optimisés : Simulation numérique CFD; Analyse FEA; Conception assistée par ordinateur; Fabrication additive métallique; Usinage et soudure FSW (Friction Stir Welding).

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Thermavant Technologies LLC

BOOTH 5

Activities

Company Description: ThermAvant Technologies delivers solutions to complex thermal management challenges, enabling our partners to reach new levels of efficiency and performance. Specializing in advanced Oscillating Heat Pipe (OHP) technology, we develop precision-engineered solutions that maximize performance while minimizing Size, Weight, Power, and Cost (SWaP-C) and reduced delivery Time. With optimized designs, proprietary manufacturing tools, and the rigorous standards of our AS9100D-certified facility, we have innovative thermal systems trusted by both government and commercial sectors—including 10 of the top 18 U.S. defense contractors. When performance matters, ThermAvant delivers.

Products

When performance matters, ThermAvant delivers.
OHP Heat Frames, OHP Radiators, OHP Chassis, Cold Plates, OHP Battery Packages, OHP Thermal Straps, High Temp OHPs, OHP Air Cooled Heat Sinks, OHP Packages and Heat Spreaders,
OHP Heat Exchangers

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ThermAvant Technologies
-
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Wattdesign

BOOTH 17

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Activities

Wattdesign is a leading specialist in **electronic equipment cooling and data center**, empowering industries to achieve optimal thermal management.
As a pioneer in integrating **Digital Twins** for electronic equipment and data centers, Wattdesign delivers advanced tools, developed by **Cadence Design Systems**—a global leader in electronic design—leverage **virtual 3D models** enhanced by numerical simulations. These simulations cover **thermal (CFD), and electrical phenomena**, ensuring precision and reliability.
With our solutions, engineers and designers can **innovate, simulate, and validate** next-generation cooling strategies for increasingly compact and high-power systems.

Products

Celsius EC Solver is a cutting-edge software for electronics cooling simulation, enabling rapid and precise thermal analysis of electronic systems.

Developed by Cadence, it tackles complex thermal and cooling challenges faced by electronic system designers today.

The tool leverages a powerful calculation engine and advanced meshing technology to model and analyze intricate designs, reducing failure risks and optimizing thermal performance.

It simulates fluid flow and heat transfer in complex systems, addressing convection, conduction, and radiation using proprietary multi-level unstructured meshing (MLUS).

It analyzes airflow, temperature, and heat transfer in electronic assemblies, as well as natural/forced convection, solar heating, and liquid cooling.

Key Features:

- User-friendly: Intuitive interface with automated features, allowing users to focus on thermal problem-solving.
- Model integration: Seamless import of mechanical and electronic CAD models, saving setup time by filtering irrelevant data.
- Mesh generation: Automated meshing with manual options for experts.
- Efficiency: Optimized computing time through high-performance solvers and mesh generators, handling tens of millions of meshes quickly.

NEXT IMAPS EVENTS CALENDAR

2027

17th-18th March

20th THERMAL 2027,
On Micropackaging and Thermal Management,
La Rochelle, France

We are pleased to announce of the 20th Advanced Technology Workshop on Micropackaging and Thermal Management that will be held in La Rochelle on March 17th-18th, 2027. This yearly conference has grown year after year by the number of presented papers and attendees.

14th-16th September

26th EMPC 2027,
European Microelectronics Packaging Conference,
Ingolstadt, Germany

The event will present the best of microelectronics packaging and interconnection technologies, providing world-class coverage of technological innovation in the microelectronics and packaging field with contributions from both industry and academia.

2026

3th-4th June

12th MiNaPAD 2026,
Micro **Na**no Electronics **P**ackaging and **A**ssembly, **D**esign and Manufacturing Forum,
Grenoble France

26th November

16th POWER 2026
From Nano to Macro Power Electronics and Packaging European Workshop,
Tours, France

IMAPS Europe

Who We Are...

The International Microelectronics and Packaging Society (IMAPS) is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging technologies through professional education and training, interaction withindustry and networking amongst professionals and academics. Founded in 1967 as ISHM, IMAPS has professional members in 23 North American chaptersand 21 international chapters.

From the founding of ISHM in the 1960s toits evolutioninto IMAPS today, the Microelectronics and Photonics community has enjoyed and benefited from the global involvement of internationals over the decades.

IMAPS Europe has friendships with IMAPS organisationsaround the world. Amongst these are close cordial contacts and conversations with our colleagues in Japan, Taiwan and North America.

IMAPS Europe comprises 13 independent local IMAPS Chapters that embrace the community of microelectronics packaging engineers throughout Europe. Their members number over 1500 individuals

plus additional corporate members in some chapters.Membership is always local to a chapter. IMAPS lberiais the newest chapter to join the IMAPS Europe community.

The IMAPS European chapters organize national and international seminars, workshops and conferences, theflagship event being the EMPC, which is held every odd year interleaved with ESTC every even year with mutualaccess to bath events.

EMPC is planned to be held every 3rd week ofSeptember in, 2027, 2029, ongoing.

EMPC 2027

The 26th European Microelectronics and Packaging Conference (EMPC) & Exhibition Ingolstadt, Germany **September 14-16, 2027**The European Microelectronics and Packaging Conference (EMPC 2027) is the premier international conference for microelectronics packaging, owned and sponsored by IMAPS-Europe and co-sponsored by IEEE- EPS. The event brings together researchers, innovators, technologists, and business and marketing managers with a shared interest in semiconductor packaging .

The program will focus on bath current industrial needs and trends, as well as on long-term academicsolutions such as:

- Advanced Packaging & System-Integration
- Materials and Processes
- Design, Modelling and Reliability
- Markets and Developments

Co-Sponsored by:

In addition to the technical sessions, EMPC will feature a comprehensive exhibition, offering companies and institutions the opportunity to present their latest products, technologies, and ser vice s. This exhibition provides an ideal platform for networking, business development, and discovering cutting-edge solutions inmicroelectronics packaging .

IMAPS France Chapter

International Microelectronics Assembly Packaging Society

IMAPS-France (French chapter) is a non-profit organization with 200 members in 2026from 110 companies or institutes in France and neighbouring countries (Belgium, Switzerland, Morocco, Spain, Portugal). IMAPS-France is one out of the 30 IMAPS chapters throughout the World Our mission is to promote and to disseminate knowledge and know-how related to the packaging and assembly of semiconductor devices.

The Board

Alexandre Val	IMAPS France President
Jean-Yves Soulier	Treasurer
Bruno Levrier	Secretary
Jean-Charles Souriau	Technical Manager

Organizer

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IMAPS - International Microelectronics Assemblyand Packaging Society - is a global community of microelectronic related engineers, scientists,

manufacturers, end-users and supply chain companies.The Society aims to support the development and growth of the Microelectronics and related industries, and to aid the transfer of knowledge and information.This is achieved through networking, seminars, workshops, short courses, publications, webinars and websites.

Members benefit from access to business networkingand events at a reduced rate; technical information

& receive society newsletters and other publications. IMAPS is the largest Microelectronic Packaging Societyin the World !

IMAPS-France (French chapter) is a non-profitorganization with 200 members in 2026 from

110 companies or institutes in France and neighbouringcountries (Belgium, Switzerland, Morocco, Spain, Portugal). IMAPS-France is one out of the 30 IMAPS chapters throughout the World.

To that end, we organize events each year, in Englishlanguage, these are namely: MiNaPAD, POWER, THERMAL and EMPC 2025 a European Event.

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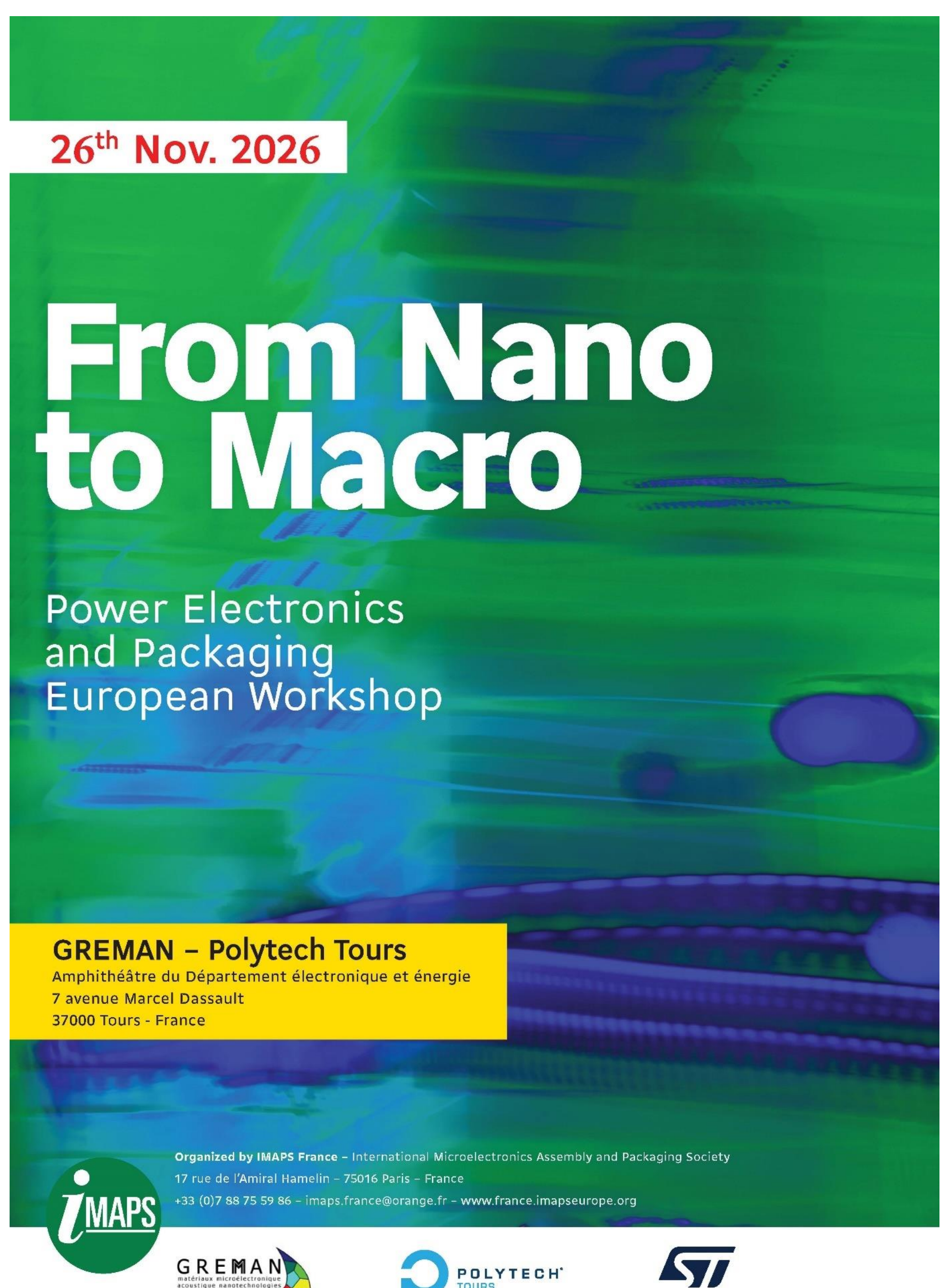

Cover interior

March 17th – 18th 2027
La Rochelle
France
Mercure Océanide
Vieux Port Sud
20th European Advanced Technology Workshop on Micropackaging and Thermal Management
Organized by IMAPS France – International Microelectronics Assembly and Packaging Society
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